

SPECIFICATION AMENDMENTS

Please replace paragraph 0004 bridging pages 1-2 with the following re-written paragraph:

[0004] The sensor array substrates are typically individually packaged in an hermetically sealed package having signal input output terminals and a clear glass or plastic lid, or window, that exposes the light-sensitive elements of the sensor below it to the incident light. Examples of such packages are disclosed in U.S. Patent 6,117,193, entitled "Optical Sensor Array Mounting and Alignment" and issued on September 12, 2000, to Thomas P. Glenn and in U.S. Patent ~~7,447,705~~ 6,117,705, entitled "Method of Making Integrated Circuit Package Having Adhesive Bead Supporting Planar Lid Above Planar Substrate" and issued on September 12, 2000, to Thomas P. Glenn et al.

Please replace paragraph 0016 on page 4 with the following re-written paragraph:

[0016] In a specific embodiment, depicted in FIG. 1, the present invention consists of a field flattening lens 10, usually a negative power lens, which is integral with a sensor package 12 containing a die 14. Field flattening lenses are generally well-known in the optics art, although not as applied to sensor packages. The die 14 is commonly a sensor, such as a CMOS (complementary metal oxide semiconductor) or CCD (charge coupled device). Such sensors are well-known, and do not form a part of the present invention.

Please replace paragraph 0018 on page 4 with the following re-written paragraph:

[0018] The field flattening lens 10 of the present invention operates by introducing the correct amount of field curvature to balance that of a lens positioned in front of it. Although shown in FIG. 1 wherein one surface 10a is curved and the opposite surface 10b is flat, the field flattening lens 10 may have one or two spherical, aspherical, or diffractive surfaces. The lens 10 may also have hybrid surfaces consisting of diffractive and/or refractive microlenses or ~~anti-aliasing~~ anti-aliasing features. Lenses having surfaces that include anti-aliasing features are well-known in the optics art.

Please replace paragraph 0022 on page 5 with the following re-written paragraph:

[0022] The pellets are heated up in a mold above a certain temperature, where a chemical reaction occurs to form the thermoset plastic. Once the chemical reaction occurs, the thermoset plastic lens 10 will not melt at any temperature, but rather will burn at some elevated temperature. The temperature of burning is typically higher than the melting temperature of a thermoplastic material and is also higher than the temperatures to which the die 14 and package 12 may be subjected to in subsequent processing, such as re-flow soldering operations.